

## Thermal Graphite foamed gasket(TGF)

-Description of raw material( Nanosized synthetic graphite powders):

It is combined thermal spreading sheet and laminated with thermally conductive Non-carrier adhesive or heat dissipation film tape. It also maximizes the thermal Spreading function by mixing heat diffusion material with nanosized synthetic graphite Powders.

-Specification of sheet:

1)Thickness(um):50-1,000+/-10% (ASTM D-374)

2)Density(g/cm<sup>3</sup>): 1.5-1.8 (ASTM D-792)

3)Thermal conductivity(XY-Horizontal):400-600W/m.K (ASTM E-1461)

4)Thermal conductivity(Z-Vertical):5-15W/m.K (ASTM E-1461)

5)Elongation resistance F.:30Mpa (ASTM D-882)

6)Bending No.(180):OK (10,000 times)

-Excellent thermal conductivity performed by applying a graphite sheet with horizontal and vertical.

-No particles by graphite surface coated with thin PET film( 30um)

-It can be produced various sizes even the silicone pad has limited thickness

-It has excellent compression elasticity by applying a heat-resistant soft foam core.

-There is no problem with bending of circuit board thanks to the excellent cushioning and lightness

-The hardness and thermal conductivity can be adjusted to be for users' needs

-This gasket delivers the heat from heat source to the heat sink or metal frame.

-It can be used to lower temperature of circuits by dispersing the heat from heat source widely.

-This TGF gasket can be easily to applied for Electronic devices such as Smart-phone, Tablet & PC, Computer, Digital Camera, Black box,LED, and any applications where applicable to all electronic products requiring Thermal solution. In recent there are demands from **TV power board and car battery.**